

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A compression assembled semiconductor package comprising:
a semiconductor die having a first major surface and a second major surface;
first and second electrodes disposed on said first and said second major surfaces,
respectively;

an insulation ring having an interior wall annularly disposed around and radially spaced from said semiconductor die, said interior wall having at least a first groove in ~~an~~ a first end portion of said insulation ring, and said interior wall having a second groove in a second end portion of said insulation ring;

a first conductive pole having a body portion which is in surface-to-surface electrical contact with said first electrode and a first pole flange extending radially from said first pole, said first pole flange having a first extending projection;

a second conductive pole having a body portion which is in surface-to-surface electrical contact with said second electrode, and a second pole flange extending radially from said second pole, said second pole flange having a second extending projection;

a first rib extending from said first pole flange and a second rib extending from said second pole flange;

and wherein each of said first extending projection and said second extending projection comprises at least one of a squared tab and a semi-circular distal end, wherein said first extending projection is forced into said first groove, and said second extending projection is forced into said second groove; and

said semiconductor die being held in place between said first pole and said second pole as a function of compressing said first and second extending projections into said first and second grooves.

2. (original) The compression assembled semiconductor package of claim 1, further comprising a control electrode disposed on a first major surface of said semiconductor die.

3. (original) The compression assembled semiconductor package of claim 2, further comprising a control signal carrier extending through said insulation ring from the exterior thereof and having an end in electrical contact with said control electrode.

Claims 4-5 (canceled).

6. (previously presented) The compression assembled semiconductor package of claim 1, wherein said first extending projection and said second extending projection extend from said first rib and said second rib, respectively.

Claim 7 (canceled).

8. (original) The compression assembled semiconductor package of claim 1, wherein at least one of said first groove and said second groove comprise at least one of a notch and a cavity.

9. (original) The compression assembled semiconductor package of claim 1, wherein said first pole includes a groove to allow said control signal carrier to reach said control electrode.

10. (original) The compression assembled semiconductor package of claim 1, wherein said semiconductor die is a thyristor.

11. (original) The compression assembled semiconductor package of claim 1, wherein said first pole includes a connection tab extending radially away from its periphery.

12. (original) The compression assembled semiconductor package of claim 1, wherein said control signal carrier comprises a control pin in electrical contact at one end thereof with said control electrode and electrically connected by a conductive strip to a lead that extends through the body of said molded plastic insulation ring.

13. (previously presented) The compression assembled semiconductor package of claim 1, wherein at least one of said first extending projection and said second extending projection comprises at least one of a tapered projection, a distal end, a reentrant cut, a stepped end and an axillary projecting edge.

Claim 14 (canceled).